

ABSTRACT OF THE DISCLOSURE

A contact (15) and a copper interconnect line (16) as an uppermost interconnect layer are buried in an interlayer insulating film (14). A pad area (17) including aluminum alloy (such as AlCu or AlSiCu) is buried in a predetermined area of the copper
5 interconnect line (16). A gold wire (18) is bonded to the pad area (17).